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PLATINUM PALLADIUM SILVER CONDUCTOR 9566

ESL 9566 is a general purpose conductor for use in hybrid circuits. It has excellent solderability and low resistivity. It makes good electrical contact with ESL 8836 gold conductor, thermosonic gold wire bonding, and with ESL 8835-1B, thermal printhead terminations. ESL 9566 can also be used with other ESL gold inks in high reliability circuits.

PASTE DATA

RHEOLOGY:	Thixotropic, screen printable paste
VISCOSITY: (Brookfield RVT, ABZ Spindle, 10 rpm, 25.5±0.5°C)	225±25 Pa•s
BONDING MECHANISM:	Mixed
SHELF LIFE:(25°C)	6 months

PROCESSING

SCREEN MESH/EMULSION:	325/12.5 µm
LEVELING TIME: (25°C)	5-10 minutes
DRYING AT 125°C:	10-15 minutes
FIRING RANGE:	850°C-930°C
OPTIMUM:	850°C
TIME AT PEAK:	10-12 minutes
RATE OF ASCENT/DESCENT:	60°C-100°C/minute
SUBSTRATE OF CALIBRATION:	96% alumina, beryllia
THINNER:	ESL 401

ESL Affiliates
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TYPICAL PROPERTIES

FIRED THICKNESS:	12.5±2.5 µm
RESISTIVITY:	≤ 8 mΩ/sq.
PRINTING RESOLUTION: (Line/Space)	500 µm x 500 µm
SOLDER WETTABILITY: (RMA flux, 5 sec. dip) (62Sn/36Pb/2Ag, 220°C±5°C)	Excellent
SOLDER LEACH: (No. of 10 sec. dip to double resistance of 0.25 mm wide x 100 mm long conductor)	
62 Sn/36 Pb/2 Ag (220°C±5°C)	10
ADHESION: (90° pull, 2.0 mm x 2.0 mm pads, 62 Sn/36 Pb/2 Ag)	
Initial pull strength:	≥ 70 N
Aged 48 hours at 150°C:	≥ 60 N
ULTRASONIC WIRE BOND:	
(25 µm Al wire)	6.0-6.2 g
(Aged 48 hours at 150°C)	4.5-5.0 g
THERMOSONIC WIRE BOND:	
(25 µm Au wire)	5.5-6.5 g

9566 9810-C